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1. TSic 206/203/201/306/316/303/301

The TSic series of temperature sensor ICs are specifically designed as a low-power solution for temperature measurement in building automation, medical/pharma technologies, industrial and mobile applications. The TSic provides a simple temperature measurement and achieves outstanding accuracy combined with long term stability.

The TSic has a high precision bandgap reference with a PTAT (proportional-to-absolute-temperature) output, a low-power and high-precision ADC and an on-chip DSP core with an EEPROM for the precisely calibrated output signal. The TSic temperature sensor is fully calibrated, meaning no further calibration effort is required by the customer.

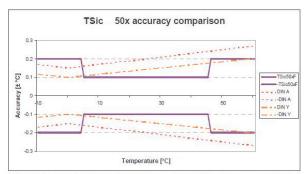


Figure 1: Comparison of TSic <--> platinum sensor accuracy

Extended long wires (> 10 m) will not influence the accuracy. The TSic is available with digital (ZacWireTM, TSic x06), analog (0 V to 1V, TSic x01) or ratiometric (10 % to 90 % V⁺, TSic x03) output signal. The low power consumption of about 35 μ A makes it suitable for many applications.

With an accuracy of ± 0.3 K in a temperature range of 80 K (e.g. ± 10 °C to ± 90 °C), the TSic sensors are more accurate than a class F0.3 (IEC60751) platinum sensor. The tolerances of the TSic and F 0.3 and F 0.15 platinum sensors are compared in Figure 1. With a standard calibration, the TSic 30x is more accurate than a F 0.3 platinum sensor in the range of ± 10 °C to ± 110 °C. The range can be shifted up or downwards to reach a high accuracy between e.g. ± 30 °C to ± 50 °C.

Output examples		e: -50 °C to +150 °C	
Temp (°C)	Digital Values (TSic x06)	Analog 0 V to 1 V (TSic x01)	Analog Ratiometric 10 % to 90 % ($V^+ = 5.0 \text{ V}$) (TSic x03)
-50 ¹⁾	0x000	0.000	10 % V+ (0.5 V)
-10	0x199	0.200	26 % V+ (1.3 V)
0	0x200	0.250	30 % V+ (1.5 V)
25	0x2FF	0.375	40 % V+ (2.0 V)
60	0x465	0.550	54 % V+ (2.7 V)
125	0x6FE	0.875	80 % V+ (4.0 V)
150 ²⁾	0x7FF	1.000	90 % V+ (4.5 V)

1) LT = -50 $\,$ 2) HT = 150 as standard value for the temperature calculation

Formulas for the output signal [°C]:

Analog output (0 V to 1 V):	T = Si	g [V] x (HT - LT) + LT	[°C]
Ratiometric output (10 % to 90 %):	T =	Sig [V] -0.1	x (HT - LT) + LT [°C]
Digital output - 11 bit:	T =	Digital signal 2047	x (HT - LT) + LT [°C]
Digital output - 14 bit (TSic 316):	T =	Digital signal 16383	x (HT - LT) + LT [°C]

LT: Lower temperature limit $[= -50 \, ^{\circ}C]$ V+: Supply voltage [V]

HT: Higher temperature limit [= +150 °C] Sig[V]: Analog/ratiometric output signal [V]













2. TSic 506F/503F/516/501F

The TSic series of temperature sensor ICs are specifically designed as a low-power solution for temperature measurement in building automation, medical / pharma technologies, industrial and mobile applications. The TSic provides a simple temperature measurement and achieves outstanding accuracy combined with long term stability. The TSic has a high precision bandgap reference with a PTAT (proportional-to-absolute-temperature) output, a low-power and high-precision ADC and an on-chip DSP core with an EEPROM for the precisely calibrated output signal. The TSic temperature sensor is fully calibrated, meaning no further calibration effort is required by the customer. With an accuracy of $\pm 0.1~\text{K}$ in a range of 40 K (e.g. $\pm 5~\text{C}$ to $\pm 45~\text{C}$), the sensor is more accurate than a class F0.1 (IEC 60751) platinum sensor.

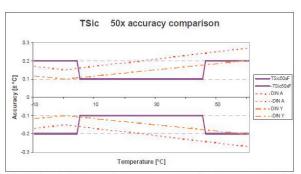


Figure 1: Comparison of TSic <--> platinum sensor accuracy

Extended long wires (> 10 m) will not influence the accuracy. The TSic is available with digital (ZacWireTM, TSic 506F), analog (0 V to 1 V, TSic 501F) or ratiometric (10 % to 90 % V $^+$, TSic 503F) output signal. The low power consumption of about 35 μ A makes it suitable for many applications.

Output Examples	ange: -10 °C to +60 °C		
Temp (°C)	Digital Values (TSic x06)	Analog 0 V to 1 V (TSic x01)	Analog Ratiometric 10 % to 90 % (V^+ = 5.0 V) (TSic x03)
< -10 to -10 ¹⁾	0x000	0.000	10 % V+ (0.5 V)
0	0x124	0.143	21.4 % V+ (1.07 V)
25	0x3FF	0.500	50 % V+(2.5 V)
$+60^2$ to $> +60$	0x7FF	1.000	90 % V ⁺ (4.5 V)

²⁾ HT = 60 as standard value for the temperature calculation

Formulas for the output signal [°C]:

Analog output (0 V to 1 V): $T = Sig [V] x (HT - LT) + LT [^{\circ}C]$

Ratiometric output (10 % to 90 %): $T = \frac{\frac{\text{Sig}[V]}{V^+[V]}}{0.8} \times (\text{HT-LT}) + \text{LT} \quad [^{\circ}\text{C}]$

Digital output - 11 bit: $T = \frac{\text{Digital signal}}{2047} \times (\text{HT - LT}) + \text{LT [°C]}$

Digital output - 14 bit (TSic 516): $T = \frac{\text{Digital signal}}{16383} \times (\text{HT - LT}) + \text{LT [°C]}$

LT: Lower temperature limit [= -10 °C] V+: Supply voltage [V]

HT: Higher temperature limit $[= +60 \, ^{\circ}C]$ Sig[V]: Analog/ratiometric output signal [V]













3. TSic 716

The TSic series of temperature sensor ICs are specifically designed as a low-power solution for temperature measurement in building automation, medical/pharma technologies, industrial and mobile applications. The TSic provides a simple temperature measurement and achieves outstanding accuracy combined with long term stability. The TSic has a high precision bandgap reference with a PTAT (proportional-to-absolute-temperature) output, a low-power and high-precision ADC and an on-chip DSP core with an EEPROM for the precisely calibrated output signal. The IST AG TSic sensor is fully tested and calibrated to ensure the guaranteed accuracy.

Output Examples	Temperature Range: -10 °C to +60 °C
Temp (°C)	Digital
+35	0x2925
+40	0x2DB7
+45	0x3249

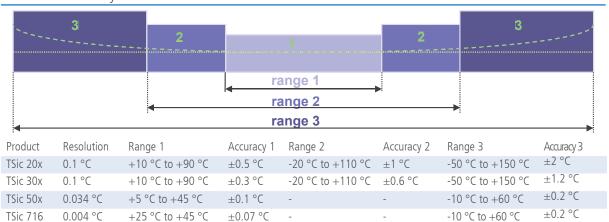
Formulas for the output signal [°C]:

Digital output: $T = \frac{\text{Digital signal}}{16383} \times (\text{HT - LT}) + \text{LT [°C]}$

LT: Lower temperature limit $[= -10 \, ^{\circ}\text{C}]$ HT: Higher temperature limit $[= +60 \, ^{\circ}\text{C}]$

V+: Supply voltage [V]

4. TSic Accuracy Overview¹⁾



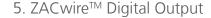
1) Range 1 can be shifted to a customer specific temperature



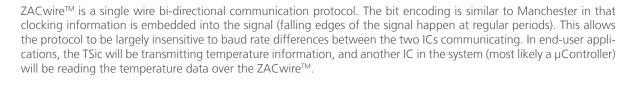








5.1 TSic ZACwire™ Communication Protocol





5.2 Temperature Transmission Packet from a TSic

The TSic transmits 1-byte packets. These packets consist of a start bit, 8 data bits, and a parity bit. The nominal baud rate is 8 kHz (125 µsec bit window). The signal is normally high. When a transmission occurs, the start bit occurs first followed by the data bits (MSB first, LSB last). The packet ends with an even parity bit.

Start Bit MSB (7)			LSB (0)	Parity (Even)	
----------------------	--	--	---------	---------------	--

Figure 1.1 – ZACwire™ Transmission Packet

The TSic provides temperature data with 11-bit or 14-bit resolution, and obviously these 11 bits or 14-bit of information cannot be conveyed in a single packet. A complete temperature transmission from the TSic consists of two packets. The first packet contains the most significant 3 bits or 6 bits of temperature information, and the second packet contains the least significant 8 bits of temperature information. There is a single bit window of high signal (stop bit) between the end of the first transmission and the start of the second transmission.

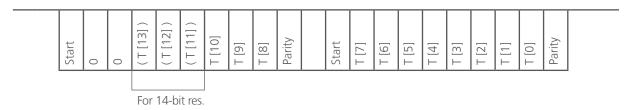
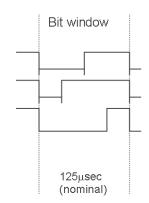


Figure 1.2 – Full ZACwire™ Temperature Transmission from TSic

5.3 Bit Encoding

The bit format is duty cycle encoded:

Start bit => 50 % duty cycle used to set up strobe time



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Perhaps the best way to show the bit encoding is with an oscilloscope trace of a ZACwire™ transmission. The following shows a single packet of 96 Hex being transmitted. Because 96 Hex is already even parity, the parity bit is zero.

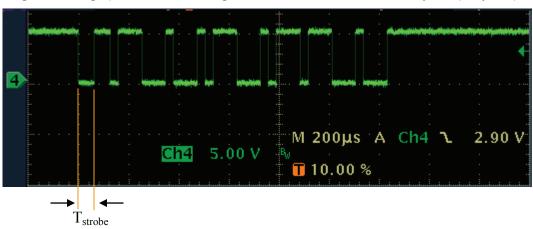


Figure 1.3 – ZACwire™ Transmission

5.4 How to Read a Packet

When the falling edge of the start bit occurs, measure the time until the rising edge of the start bit. This time (T_{strobe}) is the strobe time. When the next falling edge occurs, wait for a time period equal to T_{strobe} , and then sample the ZACwireTM signal. The data present on the signal at this time is the bit being transmitted. Because every bit starts with a falling edge, the sampling window is reset with every bit transmission. This means errors will not accrue for bits downstream from the start bit, as it would with a protocol such as RS232. It is recommended, however, that the sampling rate of the ZACwireTM signal when acquiring the start bit be at least 16x the nominal baud rate. Because the nominal baud rate is 8 kHz, a 128 kHz sampling rate is recommended when acquiring Tstrobe.

5.5 How to Read a Packet using a µController

It is best to connect the ZACwireTM signal to a pin of the μ Controller that is capable of causing an interrupt on a falling edge. When the falling edge of the start bit occurs, it causes the μ Controller to branch to its ISR. The ISR enters a counting loop incrementing a memory location (T_{strobe}) until it sees a rise on the ZACwireTM signal. When T_{strobe} has been acquired, the ISR can simply wait for the next 9 falling edges (8-data, 1-parity). After each falling edge, it waits for T_{strobe} to expire and then sample the next bit.

The ZACwireTM line is driven by a strong CMOS push/pull driver. The parity bit is intended for use when the ZACwireTM is driving long (> 2 m) interconnects to the μ Controller in a noisy environment. For systems in which the "noise environment is more friendly", the user can choose to have the μ Controller ignore the parity bit. In the appendix of this document is sample code for reading a TSic ZACwireTM transmission using a PIC16F627 μ Controller.

5.6 How Often Does the TSic Transmit?

If the TSic is being read via an ISR, how often is it interrupting the μ Controller with data? The update rate of the TSic can be programmed to one of 4 different settings: 250 Hz, 10 Hz, 1 Hz, and 0.1 Hz. This is done during calibration of the sensor on IST AG side. The standard update rate is 10 Hz (TSic 206, TSic 306, TSic 506) or 1 Hz (TSic 716). For other update rates please contact IST AG. Servicing a temperature-read ISR requires about 2.7 ms. If the update rate of the TSic is programmed to 250 Hz, then the μ Controller spends about 66 % of its time reading the temperature transmissions. If, however, the update rate is programmed to something more reasonable like 1 Hz, then the μ Controller spends about 0.27 % of its time reading the temperature transmissions.

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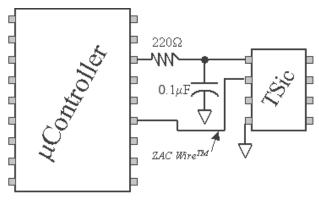


5.7 Solutions if Real Time System Cannot Tolerate the TSic Interrupting the $\mu Controller$

Some real time systems cannot tolerate the TSic interrupting the μ Controller. The μ Controller must initiate the temperature read. This can be accomplished by using another pin of the μ Controller to supply V_{DD} to the TSic. The TSic will transmit its first temperature reading approximately 65-85 ms $^{1)}$ (@RT) after power up. When the μ Controller wants to read the temperature, it first powers the TSic using one of its port pins. It will receive a temperature transmission approximately 65 ms to 85 ms later. If during that 85 ms, a higher priority interrupt occurs, the μ Controller can simply power down the TSic to ensure it will not cause an interrupt or be in the middle of a transmission when the high priority ISR finishes. This method of powering the TSic has the additional benefit of acting like a power down mode and reducing the quiescent current from a nominal 45 μ A to zero. The TSic is a mixed signal IC and provides best performance with a clean V_{DD} supply. Powering through a μ Controller pin does subject it to the digital noise present on the μ Controller's power supply. Therefore it is best to use a simple RC filter when powering the TSic with a μ Controller port pin. See the diagram below

1) This value is depending on the temperature. In lower temperatures this value can be lower too

 μ Controller powers TSic with a port pin through a simple RC filter.



5.8 Appendix A: An Example of PIC1 Assembly Code for Reading the ZACwire™

In the following code example, it is assumed that the ZACwire TM pin is connected to the interrupt pin (PORTB, 0) of the PIC and that the interrupt is configured for falling edge interruption. This code should work for a PIC running between 2 MHz to 12 MHz.

TEMP_HIGH 0X24 ;; MEMORY LOCATION RESERVED FOR TEMP HIGH BYTE **EQU** TEMP_LOW ;; MEMORY LOCATION RESERVED FOR TEMP LOW BYTE 0X25 EQU ;; THIS BYTE MUST BE CONSECUTIVE FROM TEMP_HIGH LAST LOC **EOU** 0X26 ;; THIS BYTE MUST BE CONSECUTIVE FROM TEMP_LOW **TSTROBE** EOU 0X26 ;; LOCATION TO STORE START BIT STROBE TIME 0X004 ORG ;; ISR LOCATION

.....

CODE TO SAVE ANY NEEDED STATE AND TO DETERMINE THE SOURCE OF THE ISR GOES HERE. ONCE YOU HAVE DETERMINED THE SOURCE IF THE INTERRUPT WAS A ZAC WIRE TRANSMISSION THEN YOU BRANCH TO ZAC_TX

.....

ZAC_TX: MOVLW TEMP_HIGH ;; MOVE ADDRESS OF TEMP_HIGH (0X24) TO W REG MOVWF FSR ;; FSR = INDIRECT POINTER, NOW POINTING TO TEMP_HIGH

GET_TLOW: MOVLW 0X02 ;; START TSTROBE COUNTER AT 02 TO ACCOUNT FOR

MOVWF TSTROBE ;; OVERHEAD IN GETTING TO THIS POINT OF ISR CLRF INDF ;; CLEAR THE MEMORY LOCATION POINTED TO BY FS

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STRB:	INCF	TSTROBE.1	;; INCREMENT TSTROBE
JIND.	IIVCI	I STRODE, I	,, INCINLINI ISTNOBL
	BTFSC	STATUS,Z	;; IF TSTROBE OVERFLOWED TO ZERO THEN

GOTO ;; SOMETHING WRONG AND RETURN FROM INTERRUPT **BTFSS** PORTB,0 ;; LOOK FOR RISE ON ZAC WIRE

GOTO ;; IF RISE HAS NOT YET HAPPENED INCREMENT TSTROBE STRB

CLRF BIT_CNT ;; MEMORY LOCATION USED AS BIT COUNTER ;; MEMORY LOCATION USED AS STROBE COUNTER STRB CNT BIT LOOP: **CLRF** ;; MEMORY LOCATION USED FOR EDGE TIME OUT **CLRF** TIME_OUT

WAIT_FALL: BTFSS PORTB,0 ;; WAIT FOR FALL OF ZAC WIRE ;; NEXT FALLING EDGE OCCURRED GOTO PAUSE_STRB

INCFSZ TIME_OUT,1 ;; CHECK IF EDGE TIME OUT COUNTER OVERFLOWED GOTO WAIT_FALL

GOTO RTI ;; EDGE TIME OUT OCCURRED

;; INCREMENT THE STROBE COUNTER PAUSE_STRB: **INCF** STRB_CNT,1

MOVF TSTROBE,0 ;; MOVE TSTROBE TO W REG SUBWF STRB_CNT,0 ;; COMPARE STRB_CNT TO TSTROBE BTFSS STATUS,Z ;; IF EQUAL THEN IT IS TIME TO STROBE

;; ZAC WIRE FOR DATA, OTHERWISE KEEP COUNTING GOTO PAUSE STRB

;; LENGTH OF THIS LOOP IS 6-STATES. THIS HAS TO

;; MATCH THE LENGTH OF THE LOOP THAT ACQUIRED TSTROBE

BCF STATUS,C ;; CLEAR THE CARRY

BTFSC PORTB,0 ;; SAMPLE THE ZAC WIRE INPUT

BSF STATUS,C ;; IF ZAC WIRE WAS HIGH THEN SET THE CARRY ;; ROTATE CARRY=ZAC WIRE INTO LSB OF REGISTER **RLF** INDF, 1

> ;; THAT FSR CURRENTLY POINTS TO :; CLEAR THE EDGE TIMEOUT COUN

WAIT_RISE: BTFSC PORTB,0 ;; IF RISE HAS OCCURRED THEN WE ARE DONE

> GOTO NEXT_BIT

TIME_OUT

CLRF

INCFSZ TIME_OUT,1 ;; INCREMENT THE EDGE TIME OUT COUNTER

GOTO WAIT_RISE

GOTO ;; EDGE TIME OUT OCCURRED. RTI

NEXT_BIT: **INCF** BIT CNT,1 **;; INCREMENT BIT COUNTER**

;; THERE ARE 8-BITS OF DATA MOVLW 0X08 SUBWF BIT_CNT,0 ;; TEST IF BIT COUNTER AT LIMIT **BTFSS** STATUS,Z ;; IF NOT ZERO THEN GET NEXT BIT

GOTO BIT_LOOP

CLRF TIME OUT :: CLEAR THE EDGE TIME OUT COUNTER

BTFSS WAIT PF: PORTB,0 :: WAIT FOR FALL OF PARITY

> GOTO P_RISE

INCFSZ TIME_OUT,1 ;; INCREMENT TIME_OUT COUNTER

GOTO WAIT PF

GOTO ;; EDGE TIMEOUT OCCURRED

CLRF TIME_OUT P_RISE: ;; CLEAR THE EDGE TIME OUT COUNTER

WAIT_PR: BTFSC ;; WAIT FOR RISE OF PARITY PORTB,0

GOTO NEXT_BYTE INCFSZ TIME_OUT,1 ;; INCREMENT EDGE TIME OUT COUNTER

GOTO WAIT PR

GOTO ;; EDGE TIME OUT OCCURRED

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NEXT_BYTE: INCF FSR,1 ;; INCREMENT THE INDF POINTER

MOVLW LAST_LOC

SUBWF FSR,0 ;; COMPARE FSR TO LAST_LOC ;; IF EQUAL THEN DONE BTFSS STATUS,Z

GOTO WAIT_TLOW

......

..... ;; IF HERE YOU ARE DONE READING THE ZAC WIRE AND HAVE THE DATA ;;

;; IN TEMP_HIGH & TEMP_LOW

WAIT_TLOW: CLRF TIME_OUT

; WAIT FOR FALL OF PORTB, 0 INDICATING WAIT_TLF: BTFSS PORTB,0

; START OF TEMP LOW BYTE

GOTO GET_TLOW INCFSZ TIME_OUT GOTO WAIT_TLF

GOTO RTI ; EDGE TIMEOUT OCCURRED

RTI:

;; RESTORE ANY STATE SAVED OFF AT BEGINNING OF ISR ;;

;; CLEAR INTERRUPT FLAG INTCON, INTF BSF INTCON,INTE ;; ENSURE INTERRUPT RE-ENABLED

;; RETURN FROM INTERRUPT RETFIE

......

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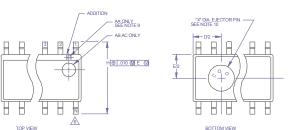


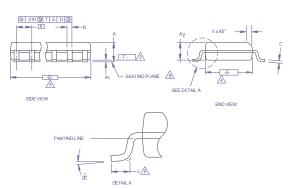


6. Die and Package Specifications

6.1 SOP-8

The following dimensional drawings are for the TSic Series SOP-8 (SOIC Narrow, 0.150) package. See Table 1.1 and Table 1.2 on the next page for the dimensions labeled in these diagrams. Unless specified otherwise, dimensions are



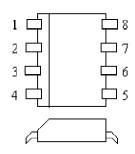


- Maximum thickness allowed is 0.015
- Dimensioning and tolerances:

Decimal	Angular	3rd Angle Projection
.xx ±0.01"	±1 °C	A -1
.xxx ±0.002"		\oplus
.xxxx ±0.0010"		

- "T" is a reference datum
- "D" & "E" are reference datums and do not include mold flash or protrusions but do include mold mismatch and are measured at the mold parting line. Mold flash and protrusions do not exceed 0.006 inches at the end and 0.01 " at the window
- 5. "L" is the length of the terminal for soldering to a substrate
- 6. "N" is the number of terminal positions
- 7. Terminal positions are shown for reference only
- Formed leads are planar with respect to one another within 0.03 " at the seating plane
- The appearance of the pin 1 marker is optionally either the round type or the rectangular type
- 10. Country of origin location on package bottom is optional and depends on assembly location
- 11. Controlling dimension: Inches
- 12. This part is compliant with JEDEC Standard MS-012, Variation AA, AB & AC

6.1.1 SOP-8 Pin Assignment



Pin	Name	Description
1	V ⁺	Supply voltage (3 V to 5.5 V)
2	Signal	Temperature output signal
4	Gnd	Ground
3.5-8	TP/NC	Test pin / NC Do not connect

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6.1.2 Inches

	Common Dimensions				Note		3		S
				Note	Variations		D		N
	MIN	NOM	MAX			MIN	NOM	MAX	
А	0.061	0.064	0.068		AA	0.189	0.194	0.196	8
Α1	0.004	0.006	0.0098		AB	0.337	0.342	0.344	14
A2	0.055	0.058	0.061		AC	0.386	0.391	0.393	16
В	0.0138	0.016	0.0192						
C	0.0075	0.008	0.0098						
D	S	ee variatio	ns	3					
Е	0.15	0.155	0.0157						
е		0.050 BS0	_						
Н	0.23	0.236	0.244						
h	0.01	0.013	0.016						
L	0.016	0.25	0.035						
Ν	S	ee variatio	ns	5					
	0 °	5 °	8°						
X	0.085	0.093	0.1						

6.1.3 Millimeters

	Com	mon Dime	nsions		Note		3		S
				Note	Variations		D		Ν
	MIN	NOM	MAX			MIN	NOM	MAX	
Α	1.55	1.63	1.73		AA	4.8	4.93	4.98	8
A1	0.127	0.15	0.25		AB	8.58	8.69	8.74	14
A2	1.4	1.47	1.55		AC	9.8	9.93	9.98	16
В	0.35	0.41	0.49						
C	0.19	0.2	0.25						
D	S	ee variatio	ns	3					
Е	3.81	3.94	3.99						
е		1.27 BSC							
Н	5.84	5.99	6.2						
h	0.25	0.33	0.41						
L	0.41	0.64	0.89						
Ν	S	See variations		5					
	0 °	5°	8°						
X	2.16	2.36	2.54						

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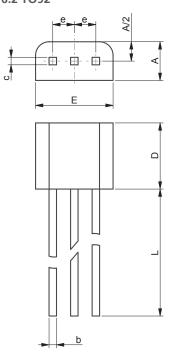








6.2 TO92

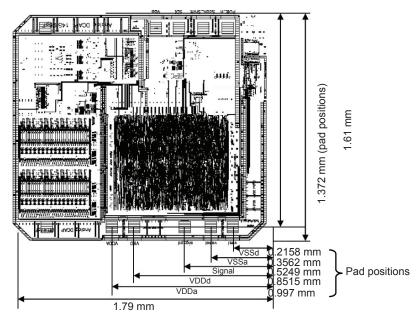


	Millin	neters	Inches		
Dimensions	MIN	MAX	MIN	MAX	
А	2.16	2.41	0.085	0.095	
b	0.41	0.495	0.016	0.0195	
С	0.41	0.495	0.016	0.0195	
D	3.61	4.01	0.14	0.16	
Е	4.37	4.77	0.172	0.188	
е	NOM. 1.27		NOM	. 0.05	
L	13	13.97	0.512	0.550	



Pin	Name	Description
3	$V^+ (V_{DD})$	Supply Voltage (3 V to 5.5 V)
2	Signal	Temperature Output Signal
1	Gnd (V _{ss})	Ground

6.3 Bare Die



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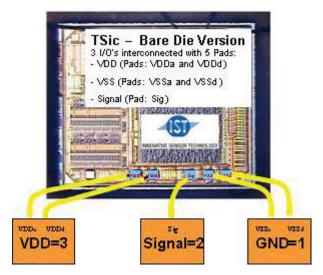




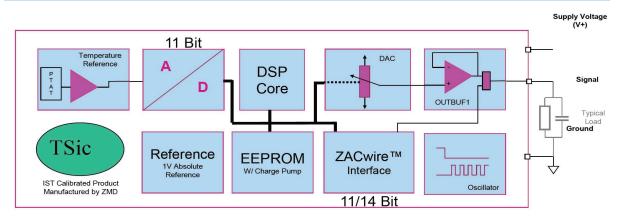
6.3.1 Bare Die Pin Assignment

Pin	Name	Description	
3	$V^+ (V_{DD})$	Supply Voltage (3 V to 5.5 V)	
2	Signal	Temperature Output Signal	
1	Gnd (V _{ss})	Ground	
Die Thickness:		390 μm	
Pad size:		68 μm x 68 μm	

The analog and digital power and ground of the chip are wired to same substrate or Flex-Pad: V_{DDA} and V_{DD} are wired to V_{DD} , and V_{SSA} and V_{SSA} are wired to Ground. The Signal pin needs only one wire.



7. TSic Block Diagram



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8. Additional Documents

	Document name:	
Data Sheet:	DTTSic20x_30x_E	DTTSic20x_30x_D
	DTTSic50x_E	DTTSic50x_D
	DTTSic716_E	DTTSic716_D
LabKit:	DTTSicLabKit_E	DTTSicLabKit_D







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